Preparation of GaN and InN for blue light emitting sources

D. Pal and D. N. Bose

Materials Science Centre, Indian Institute of Technology, Kharagpur 721 302, India

Semiconductors based on nitrides of Al, Ga and In have gained considerable interest recently for the successful implementation of bright blue and bluegreen light emitting sources. Although most of the devices are based on hexagonal (wurtzite) GaN films, cubic (zinc blende) GaN films are of great interest because of possible growth on GaAs. We have prepared GaN and InN from n-GaAs and InAs single crystal wafers by NH₃ treatment at 700°C. X-ray diffraction measurements showed both cubic and hexagonal phases of GaN and InN. N₂ plasma treatment of liquid phase epitaxy grown InGaAs at 900°C resulted in growth of separate phases of only cubic GaN and InN. Optical absorption studies on GaN showed a direct band-gap of 3.46 eV. Photoluminescence measurements on GaN showed a defect-related emission band at 2.75 eV.

THERE is now considerable interest in wide-band gap semiconductors for applications in high temperature electronics as well as blue light-emitting sources. The latter are being eagerly sought to increase the density of storage in optical memories since a decrease in wavelength by a factor of 2 from 800 nm to 400 nm is expected to increase the storage capacity by a factor of 4 (ref. 1). Recently Isamu Akasaki² and Nakamura et al.³⁻⁵ at Nichia, Japan have reported the operation of blue lasers with emission at 400 nm based on gallium nitride (GaN). Pulsed mode operation was first demonstrated², followed by cw operation for short durations.

Here we report the first work in India on the preparation of GaN and InN. This was done by treatment of GaAs and InAs single crystals with ammonia at high temperature (700°C). The grown layers were characterized by X-ray diffraction and photoluminescence measurements. Experiments on liquid phase epitaxy (LPE) grown InGaAs by N₂ plasma treatment at 900°C resulted in growth of separate phases of only cubic GaN and InN.

Nitrides are also of interest for high temperature electronics and their preparation and properties have been reviewed by Davis⁶. A programme of work on nitrides was initiated in our laboratory in the late eighties and resulted in the laser deposition of BN⁷ and AIN⁸ on GaAs and InP. Later the conductor TiN widely used as a diffusion barrier in Si technology was also deposited⁹. The series AIN-GaN-InN is attractive for LED and laser applications as these are all direct gap semiconductors with $E_{\rm g} = 5.6 \, {\rm eV}$, 3.4 eV and 2.07 eV respectively

and exhibit complete solid solubility. SiC, on the other hand, with $E_{\rm g}=2.6\,{\rm eV}$ has an indirect gap resulting in LEDs with much lower efficiencies. The technology of blue sources using the II-VI semiconductor ZnSe is also well developed, but the efficiency of GaN-based devices is expected to be higher.

We have prepared GaN and InN from n-GaAs and InAs single crystal wafers by NH₃ treatment in a home-made continuous flow reactor which was placed in a muffle furnace whose temperature was controlled to $\pm 1^{\circ}$ C. The temperature of nitridation is critical since As evolution from GaAs and InAs is known to occur above 600° C.

Chemically cleaned GaAs (100) and InAs (100) single crystal wafers were etched and dipped in dilute HF solution. Samples were loaded into the reactor immediately after taking out from the HF solution. The reactor was then purged by nitrogen flow for one hour. Nitridation was then carried out at 700°C for 2 h under NH₃ whose flow rate was 10 cc/min. The colours of GaN and InN films were found to be golden and blackish respectively. From X-ray diffraction measurements using CuK_a radiation ($\lambda = 1.54 \text{ Å}$) (Figure 1 a) three peaks related to GaN were observed at 32.8°, 35° and 39.5°. These peaks represent hexagonal (1010), (0002) and cubic GaN (002) respectively. It is known that under ambient conditions GaN has the wurtzite form and as such is grown on sapphire (Al₂O₃) substrates. However it can be grown with zinc blende structure on GaAs as a strained layer, due to appreciable lattice mismatch, i.e. 4.550 Å vs 5.653 Å. This is desirable for technological reasons since a conducting substrate simplifies device geometry and yields lower series resistance, a non-trivial problem with high band-gap materials.

X-ray diffraction peaks (Figure 1b) at 31°, 51.2°, 60.8° and 35.6° related to InN were observed from the InN/InAs samples. These peaks represent hexagonal (0020), (1100) and (2000) and cubic (200) InN respectively. Attempts to grow GaN on GaAs using NH, in r.f. plasma at 250°C were not successful. Next a lattice-matched epitaxial layer of $In_{1-x}Ga_xAs_x (x=0.47)$ grown on InP (100) by liquid phase epitaxy was taken. The layer had been fully characterized and was 4.5 μ m thick with $n = 6.7 \times 10^{16}$ cm⁻³. When this was heated in a 450 kHz induction furnace at 900-950°C in a nitrogen plasma for 2 h the surface became ash coloured. The X-ray diffraction measurements of the sample showed the formation of both InN and GaN with cubic zinc-blende structures (Figure 1 c). The larger diffraction linewidths in Figure 1 a are due to smaller grain size. Use of the Scherrer formula shows that the grain size in this case is 95-190 Å compared with 420-540 Å for Figure 1 b and 390-514 Å for Figure 1 c. This may be attributed to higher bond breaking energy for GaAs compared with InAs and lower tem-

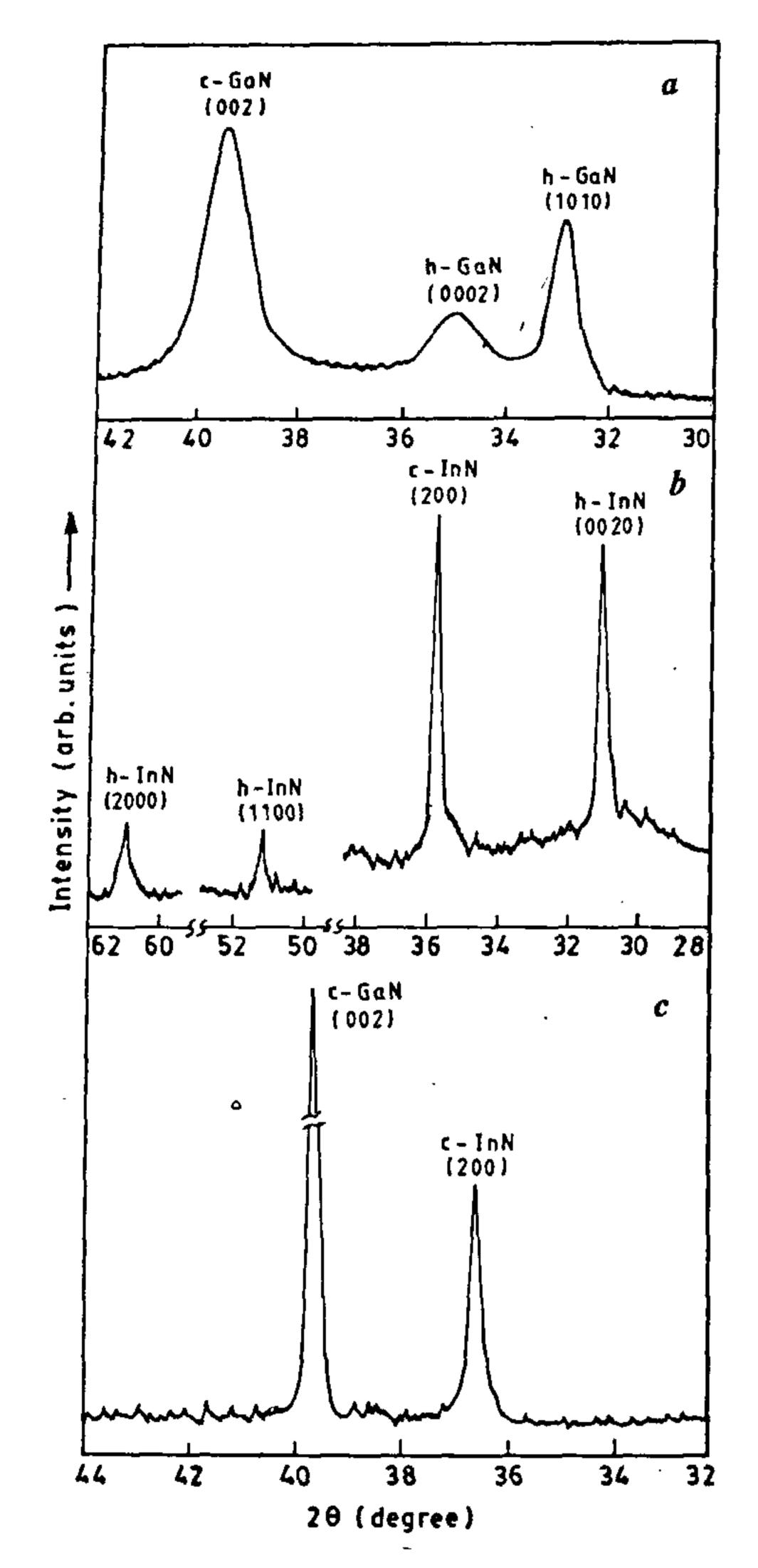


Figure 1 a-c. a, XRD scans $(\theta - 2\theta)$ of GaN obtained from NH₃-treated GaAs. b, XRD scans $(\theta - 2\theta)$ of InN obtained from NH₃-treated InAs. c. XRD scans $(\theta - 2\theta)$ of N₂ plasma-treated InGaAs.

perature of nitridation, 700°C for Figure 1 a compared with 900-950°C for Figure 1 a.

Photoluminescence (PL) measurement was carried out on GaN/GaAs and InN/InAs samples at 300 K using 330 nm emission as an excitation source from a tungsten halogen lamp, Jobin-Yvon monochromator and a photomultiplier detector. Only one broad emission band (Figure 2) with peak energy 2.75 eV was obtained. A similar broad band with peak energy 2.9 eV has been observed for polycrystalline GaN films grown on Si at 400°C (ref. 11). No photoluminescence was observed from

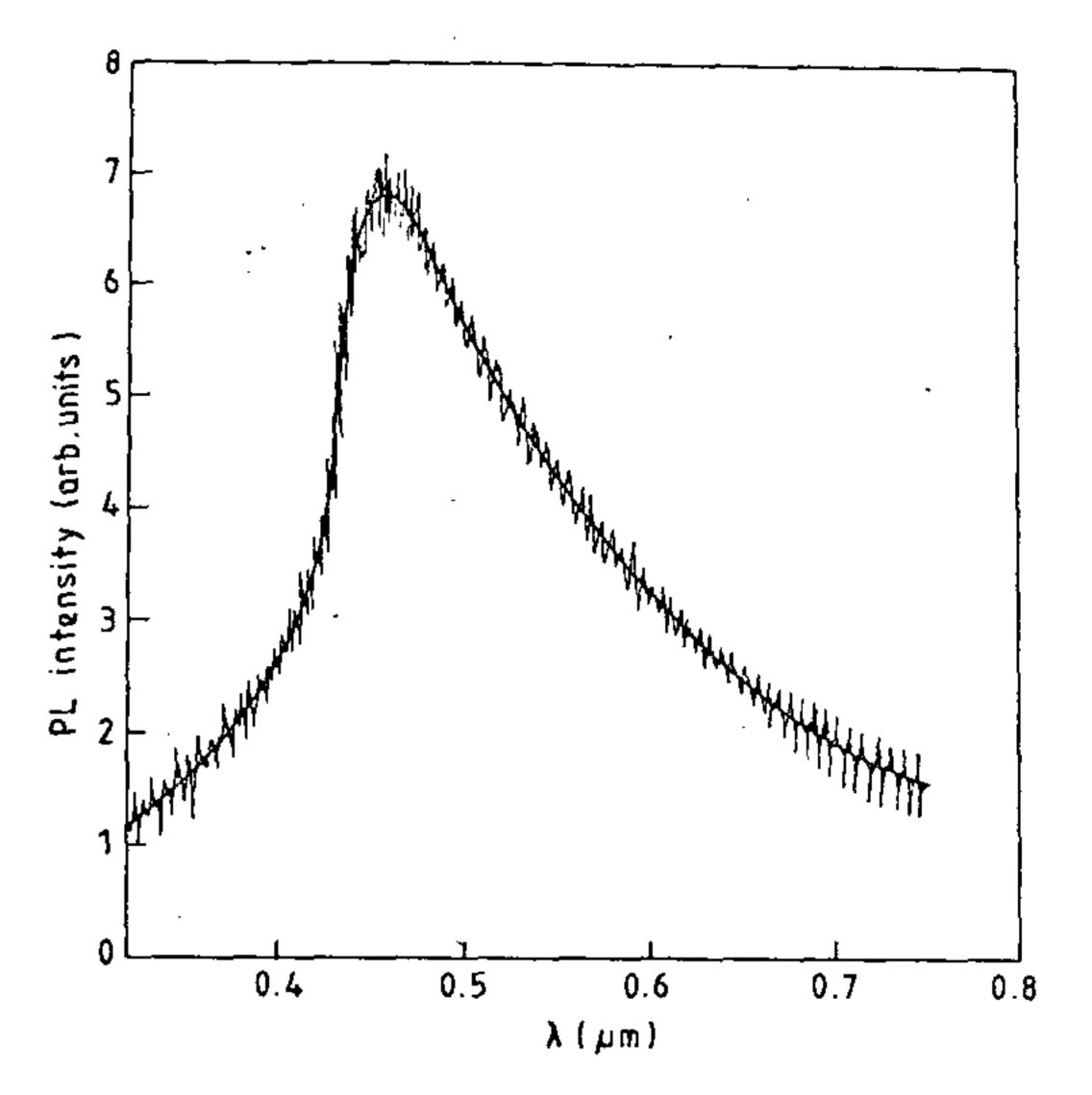


Figure 2. Photoluminescence spectrum of GaN at 300 K.

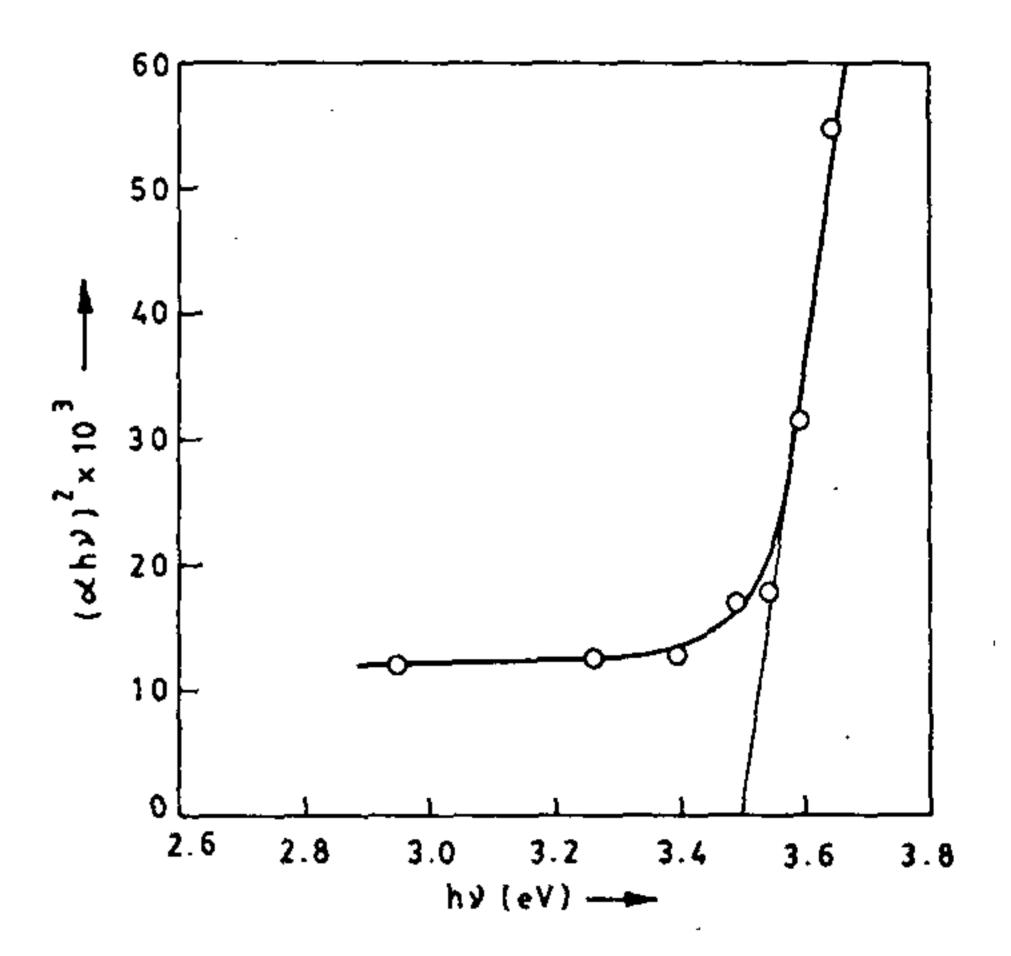


Figure 3. Optical absorption spectra of powder GaN at 300 K.

InN/InAs samples. This is intriguing since InN is considered to have a direct gap of 2.07 eV but no PI measurements have been reported from it¹². Optical absorption measurements on powder GaN sample (Figure 3) showed a direct band-gap of 3.46 eV.

Summarizing, thermal nitridation on GaAs and InA in NH₃ formed both cubic and hexagonal GaN and InN respectively while nitridation on InGaAs in N₂ plasms formed only cubic GaN and InN. Photoluminescence measurement on GaN showed a defect-related emission band at 2.75 eV and optical absorption showed a direct band-gap of 3.4 eV.

- 1. Gunshor, R. and Nuvorikko, A., Sci. Am., July 1996.
- Isamu Akasaki, Hiroshi Amano, Shigetoshi Sota, Hiromitsu Sakai, Toshiyuki Tanaka and Masajoshi Koike, Jpn. J. Appl. Phys., 1995, 34, L1517.
- 3. Nakamura, S., Senoh, M., Nagahama, S. et al., Jpn. J. Appl. Phys., 1996, 35, L174.
- 4. Nakamura, S., Senoh, M., Nagahama, S. et al., Jpn. J. Appl. Phys., 1996, 35, L217.
- 5. Nakamura, S., Senoh, M., Nagahama, S. et al., Appl. Phys. Lett., 1996, 68, 2105.
- 6. Robert F. Davis, Proc. IEEE, 1991, 79, 702.
- 7. Paul, T. K., Bhattacharya, P. and Bose, D. N., Electron. Lett., 1989, 25, 1602.
- 8. Paul, T. K., Bhattacharya, P. and Bose, D. N., Appl. Phys. Lett., 1990, 56, 2648.
- 9. Ghosh, S., Ph D thesis, Materials Science Centre, Indian Institute of Technology, Kharagpur, 1996, p. 111.
- 10. Kumar, A., Pal, D. and Bose, D. N., J. Electron. Mat., 1995, 24, 833.
- Dissanayake, A., Lin, J. Y., Jiang, H. X., Yu, Z. J and Edgar,
 J. H., Appl. Phys. Lett., 1994, 65, 2317.
- 12. James H. Edgar (ed.), Properties of Group III Nitrides, INSPEC, IEE, London, UK, 1994, p. 232.

ACKNOWLEDGEMENT. We are grateful to the National Laser Programme for a project on 'Semiconductor Lasers' under which this work was carried out.

Received 19 December 1996; revised accepted 17 March 1997

Detection of the *lcr* gene in *Yersinia* pestis responsible for the recent outbreak of plague in India

S. S. Lahiri and B. S. Karothia

Defence R&D Establishment, Jhansi Road, Gwalior 474 002, India

Rapid detection of plague bacilli is particularly germane to plague epidemiology since untreated bubonic plague can rapidly progress to septicaemic or pneumonic state. A 1.3 kb Hind-III/Xho-I DNA fragment from the plasmid pCd-1 which codes for the low Ca²⁺ response of Yersiniae spp. has been used to screen the isolates of Y. pestis obtained from the recent outbreak at Beed and Surat. The probe discriminated Y. pseudotuberculosis, diarrhoeagenic Escherichia coli, Klebsiella pneumoniae, Salmonella typhi and Shigella dysenteria from Y. pestis and Y. enterocolitica. Both radioactive and non-radioactive probes gave excellent result.

The once dreaded bacteria, Y. pestis is known to carry three plasmids of 9.5 kb, 70 kb and 95 kb size¹. While the 9.5 kb (pPst) and 95 kb (pFra) plasmids code for the pesticine and F1 antigen respectively, the 70 kb

(pCad) plasmid is responsible for the low calcium response (LCR). Expression of virulence (V-antigen) is controlled by the *lcr* gene².

Virulent Yersiniae spp. can be detected by the presence of the LCR plasmid which, besides conferring virulence to the microorganism, makes the bacteria dependent on Ca²⁺ for growth at 37°C, expression of novel outer membrane protein called Yersinia outer protein (Yop), increased hydrophobicity, increased affinity to crystal violet and congo red, a tendency to agglutinate in media containing mammalian serum or enhanced resistance to bactericidal effects of normal human serum³. Although these parameters can be used for in vitro detection of the microorganism, they are reported to be not reliable tests³. Laboratory screening requires animal passages to isolate a pure culture, phage sensitivity typing, immunofluorescent antibody against fraction-1 (a major capsular antigen), etc. Screening by these methods is expensive and time-consuming. Detection at the nucleic acid level circumvents all the above limitations and provides a rapid and sensitive method for its specific detection.

In the present study, an attempt has been made to detect the presence of *lcr* gene in *Y. pestis* by DNA probe in different human and rodent isolates obtained during the recent outbreak at Beed and Surat districts. The other two virulent non-pestis *Yersiniae*, which include *Y. pseudotuberculosis* and *Y. enterocolitica* and other diarrhoeagenic enterobacteria like *Escherichia coli*, *Klebsiella pneumoniae*, *Shigella dysenteriae* and *Salmonella typhi* were also tested both by radioactive and non-radioactive DNA probes.

The test samples used comprised of 11 clinical isolates of Y. pestis from pneumonic patients of Beed district and Surat city: seven isolates from rodents, Y. pestis strain no. A-1122 which do not carry the LCR plasmid; Y. pseudotuberculosis strain no. 1A which was kindly supplied by May C. Chu, WHO Collaborating Centre at Centre for Disease Control, Fort Collins, USA; the Y. enterocolitica strain no. 0:9 IP 383 was kindly provided by Elizabeth Carniel, WHO Collaborating Centre, Institute Pasteur, Paris. Samples of E. coli, K. pneumoniae, S. dysenteriae and S. typhi, available in DRDE, were also tested simultaneously.

Bacterial cultures (24 nos) were scraped from agar plates and each resuspended in 100 µl of 0.5 M Tris.HCl (pH 8.0), 0.1 M sodium chloride and 0.01 M ethylene diamine tetraacetic acid (EDTA) in different eppendorf tubes and lysed by lysozyme followed by heat treatment.

The 1.3 kb restriction fragment that has been used as the DNA probe, contained the 3' end of lcr-R, the complete lcr-G and part of the lcr-V (virulence antigen) gene of the 70 kb LCR plasmid pCD-1. E. coli with the recombinant plasmid vector pES6-1, which contains the above as well as the lcr-H, yop-B and yop-D genes